

Keywords:

Article number:

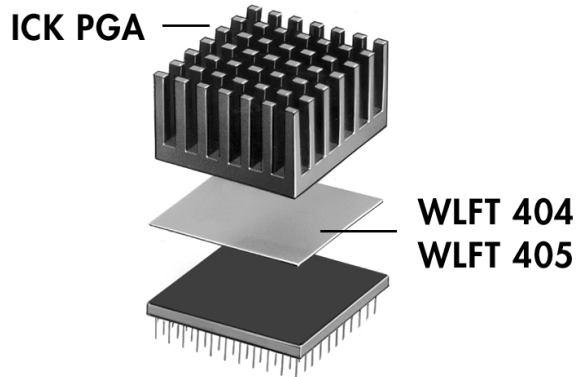
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Product groups:

- Profile heatsinks and fluid coolers
- Heatsinks and active heatsinks for processors
- Finger-shaped heatsinks
- Cooling aggregates
- Accessories for electronic components

Product group:

Heatsinks and active heatsinks for processors > Heatsinks for PGA

 Heatsinks for PGA / **ICK PGA 6 x 6 x 14**


14 x 14 x 14 mm, for IC design PGA and others

Parameters of article ICK PGA 6 x 6 x 14

R_{th} [K/W]	18.6
dissipation loss [W]	6.4
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	14
height [mm]	14
plate thickness [mm]	2.5
length on stock [mm]	14
surface treatment	black anodised

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Accessories/ related articles

[Thermally conductive foil both sides adhesive / WLFT 404 14 x 14](#)
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